

2MBI400XDE120-50

IGBT Modules

Power Module (X series)
1200V / 400A / 2-in-1 package

■ Features

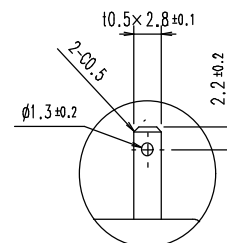
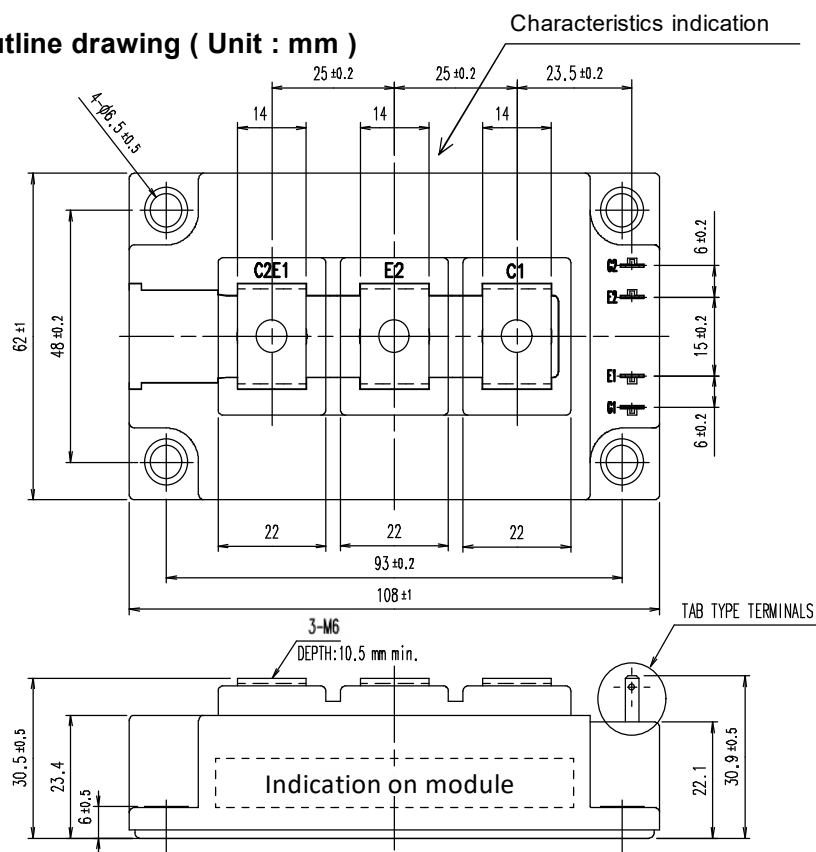
- Low $V_{CE(sat)}$
- High speed switching
- Low Inductance Module structure

■ Applications

- Inverter for Motor Drives, AC and DC Servo Drives
- Uninterruptible Power Supply Systems,
- Industrial machines, such as Welding machines

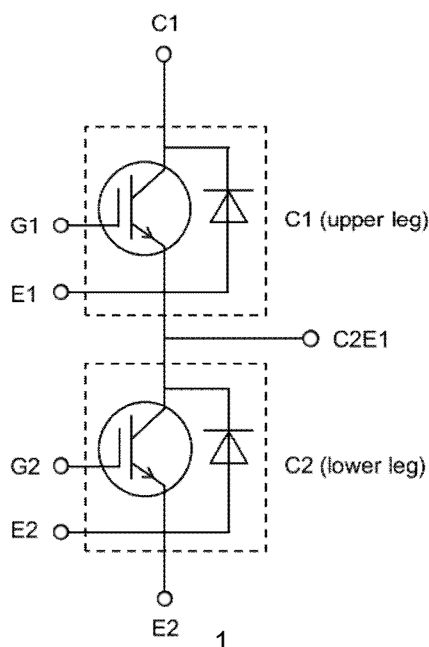


■ Outline drawing (Unit : mm)



DETAIL TAB TYPE TERMINALS

■ Equivalent circuit



Weight: 370g(typ.)

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■ Absolute maximum ratings (at $T_c = 25^\circ\text{C}$ unless otherwise specified)

Items		Symbols	Conditions	Maximum ratings	Units
Collector-Emitter voltage, Gate-Emitter short-circuited		V_{CES}		1200	V
Gate-Emitter voltage, Collector-Emitter short-circuited		V_{GES}		± 20	V
Collector current		I_C	Continuous $T_c = 100^\circ\text{C}$	400	A
Repetitive peak collector current		I_{CRM}	1ms	800	
Forward current		I_F		400	
Repetitive peak forward current		I_{FRM}	1ms	800	
Total power dissipation		P_{tot}	1 device	3000	W
Virtual junction temperature		T_{vj}		175	$^\circ\text{C}$
Operating virtual junction temperature		T_{vjop}		175	
Case temperature		T_c		125	
Storage temperature		T_{stg}		-40 ~ 125	
Isolation voltage	Between terminal and copper base (*1)	V_{isol}	AC: 1min.	4000	Vrms
Mounting torque of screws to heat sink		M_s	M5 or M6	3.0 ~ 6.0	N m
Mounting torque of screws to terminals		M_t	M6	2.5 ~ 5.0	

(*1) All terminals should be connected together during the test.

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■ Electrical characteristics (at $T_{vj}=25^{\circ}\text{C}$ unless otherwise specified)

Items	Symbols	Conditions		Characteristics			Units
				min.	typ.	max.	
Collector-Emitter cut -off current, Gate-Emitter short - circuited	I_{CES}	$V_{GE} = 0V$ $V_{CE} = 1200V$		-	-	200	μA
Gate leakage current, Collector-Emitter short-circuited	I_{GES}	$V_{CE}=0V, V_{GE}=\pm 20V$		-	-	400	nA
Gate-Emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = 20V$ $I_C = 400mA$		6.0	6.5	7.0	V
Collector-Emitter saturation voltage	$V_{CE(sat)}$ (terminal)	$V_{GE} = 15V$ $I_C = 400A$	$T_{vj}=25^{\circ}C$	-	1.55	2.00	V
	$V_{CE(sat)}$ (chip)		$T_{vj}=25^{\circ}C$	-	1.40	1.85	
			$T_{vj}=125^{\circ}C$	-	1.70	-	
			$T_{vj}=150^{\circ}C$	-	1.80	-	
			$T_{vj}=175^{\circ}C$	-	1.85	-	
Internal gate resistance	r_g	-		-	2.25	-	Ω
Input capacitance	C_{ies}	$V_{CE}=10V, V_{GE}=0V, f=1MHz$		-	46	-	nF
Output capacitance	C_{oes}			-	1.6	-	
Reverse transfer capacitance	C_{res}			-	0.42	-	
Gate charge	Q_G	$V_{CC} = 600V, I_C = 400A$ $V_{GE} = -15 \rightarrow +15V$		-	2950	-	nC
Forward voltage	V_F (terminal)	$V_{GE} = 0V$ $I_F = 400A$	$T_{vj}=25^{\circ}C$	-	1.75	2.20	V
	V_F (chip)		$T_{vj}=25^{\circ}C$	-	1.60	2.05	
			$T_{vj}=125^{\circ}C$	-	1.60	-	
			$T_{vj}=150^{\circ}C$	-	1.60	-	
			$T_{vj}=175^{\circ}C$	-	1.55	-	
Turn-on delay time (*1)	$t_{d(on)}$	$V_{CC} = 600V$ $I_C, I_F = 400A$ $V_{GE} = +15/-15V$ $R_G = 1\Omega$ $L_S = 30\text{ nH}$	$T_{vj}=25^{\circ}C$	-	380	-	ns
			$T_{vj}=125^{\circ}C$	-	380	-	
			$T_{vj}=150^{\circ}C$	-	380	-	
			$T_{vj}=175^{\circ}C$	-	380	-	
Rise time (*1)	t_r		$T_{vj}=25^{\circ}C$	-	80	-	
			$T_{vj}=125^{\circ}C$	-	90	-	
			$T_{vj}=150^{\circ}C$	-	90	-	
			$T_{vj}=175^{\circ}C$	-	90	-	
Turn-off delay time (*1)	$t_{d(off)}$		$T_{vj}=25^{\circ}C$	-	360	-	
			$T_{vj}=125^{\circ}C$	-	390	-	
			$T_{vj}=150^{\circ}C$	-	400	-	
			$T_{vj}=175^{\circ}C$	-	395	-	
Fall time (*1)	t_f		$T_{vj}=25^{\circ}C$	-	125	-	
			$T_{vj}=125^{\circ}C$	-	185	-	
			$T_{vj}=150^{\circ}C$	-	200	-	
			$T_{vj}=175^{\circ}C$	-	220	-	
Reverse recovery time	t_{rr}		$T_{vj}=25^{\circ}C$	-	205	-	
			$T_{vj}=125^{\circ}C$	-	445	-	
			$T_{vj}=150^{\circ}C$	-	505	-	
			$T_{vj}=175^{\circ}C$	-	570	-	

(*1) Turn on time (t_{on}) = $t_{d(on)} + t_r$, Turn off time (t_{off}) = $t_{d(off)} + t_f$

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■ Electrical characteristics (at $T_{vj}=25^{\circ}\text{C}$ unless otherwise specified)

Items	Symbols	Conditions		Characteristics			Units
				min.	typ.	max.	
Turn-on energy	E_{on}	$V_{\text{CC}} = 600\text{V}$ $I_{\text{C}}, I_{\text{F}} = 400\text{A}$ $V_{\text{GE}} = +15/ -15\text{V}$ $R_{\text{G}} = 1\ \Omega$ $L_{\text{S}} = 30\ \text{nH}$	$T_{\text{vj}}=25^{\circ}\text{C}$	-	23.6	-	mJ
			$T_{\text{vj}}=125^{\circ}\text{C}$	-	37.4	-	
			$T_{\text{vj}}=150^{\circ}\text{C}$	-	40.9	-	
			$T_{\text{vj}}=175^{\circ}\text{C}$	-	46.0	-	
Turn-off energy	E_{off}		$T_{\text{vj}}=25^{\circ}\text{C}$	-	27.0	-	
			$T_{\text{vj}}=125^{\circ}\text{C}$	-	33.0	-	
			$T_{\text{vj}}=150^{\circ}\text{C}$	-	34.5	-	
			$T_{\text{vj}}=175^{\circ}\text{C}$	-	35.7	-	
Reverse recovery energy	E_{rr}		$T_{\text{vj}}=25^{\circ}\text{C}$	-	9.8	-	
			$T_{\text{vj}}=125^{\circ}\text{C}$	-	19.7	-	
			$T_{\text{vj}}=150^{\circ}\text{C}$	-	22.1	-	
			$T_{\text{vj}}=175^{\circ}\text{C}$	-	25.7	-	

NOTICE:

The external gate resistance (R_G) shown above is one of our recommended value for the purpose of minimum switching loss. However the optimum R_G depends on circuit configuration and/or environment. We recommend that the R_G has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

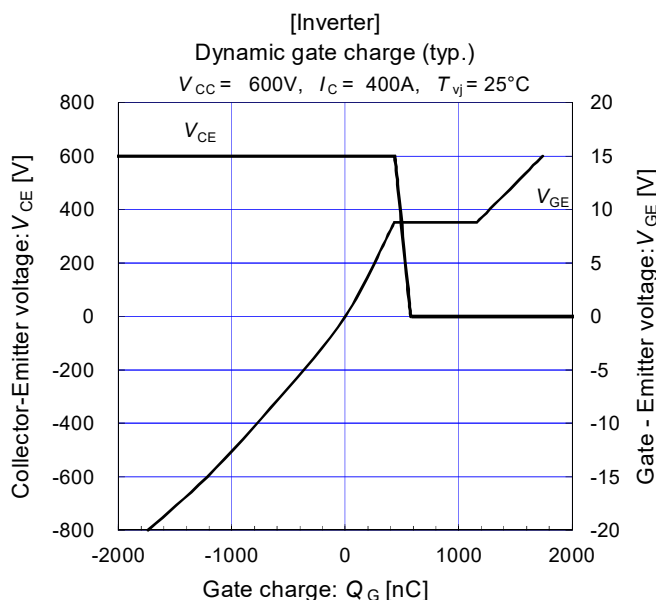
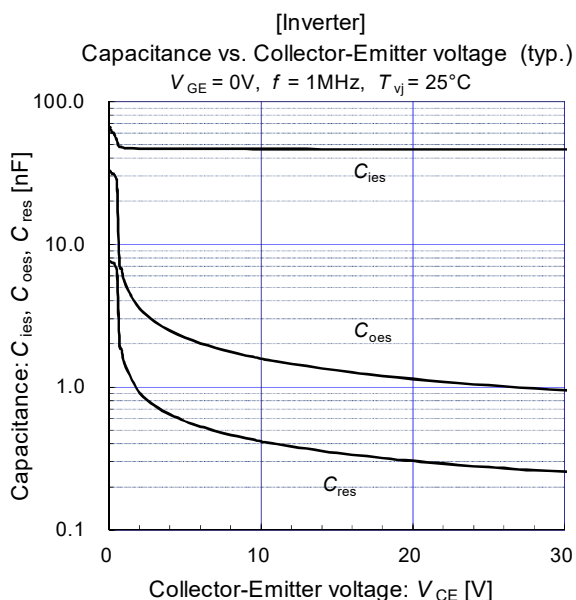
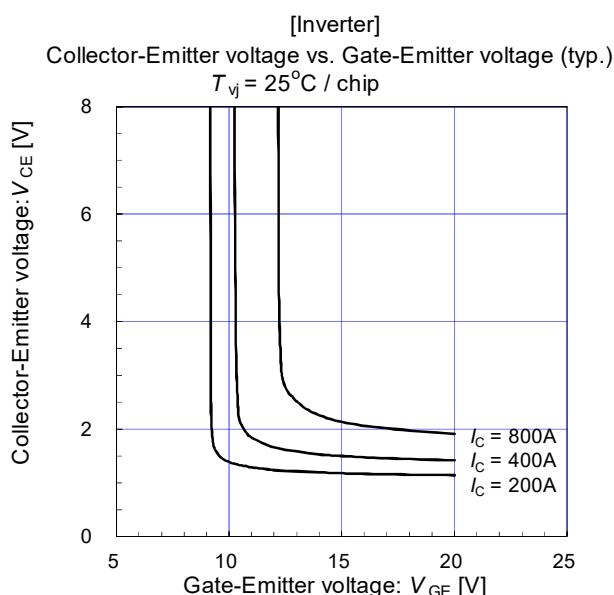
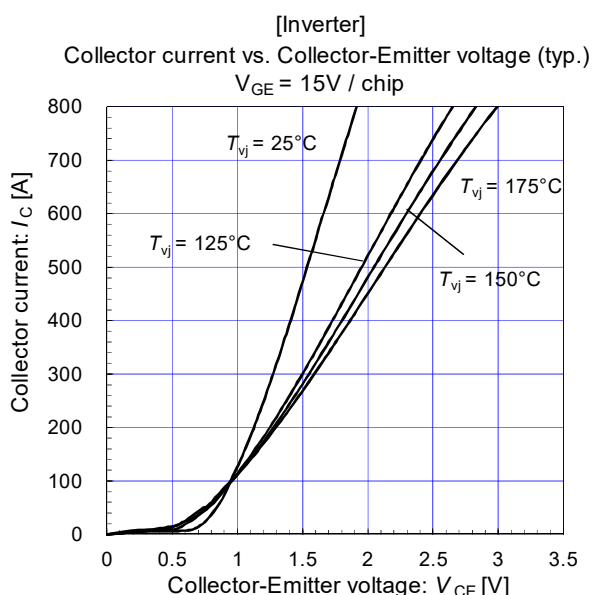
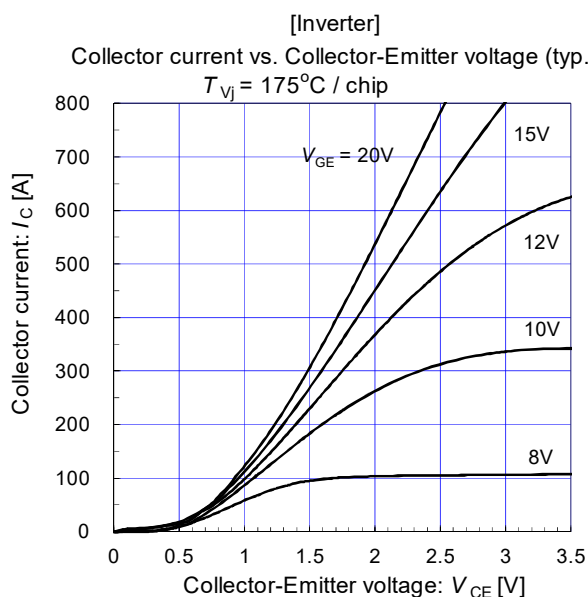
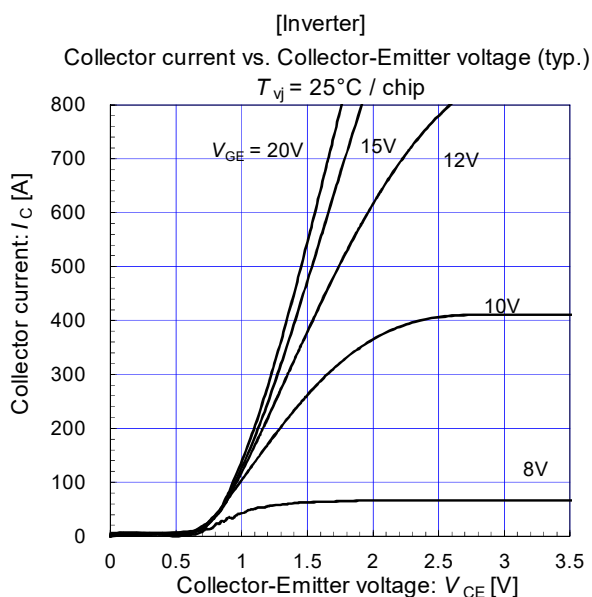
■ Thermal resistance characteristics

	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance (1device)	$R_{th(j-c)}$	IGBT	-	-	0.050	K/W
		FWD	-	-	0.084	
Thermal resistance case to heat sink (1IGBT + 1FWD) (*1)	$R_{th(c-s)}$	with 1 W/(m·K) thermal grease	-	0.0125	-	

(*1) This is the value which is defined mounting on the additional heat sink with thermal grease.

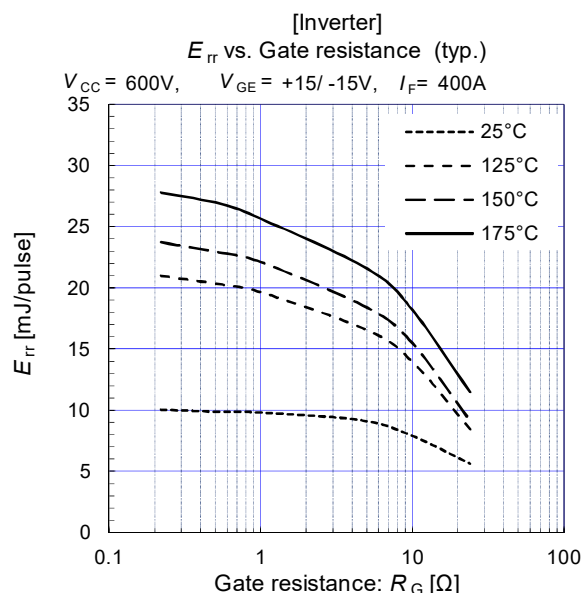
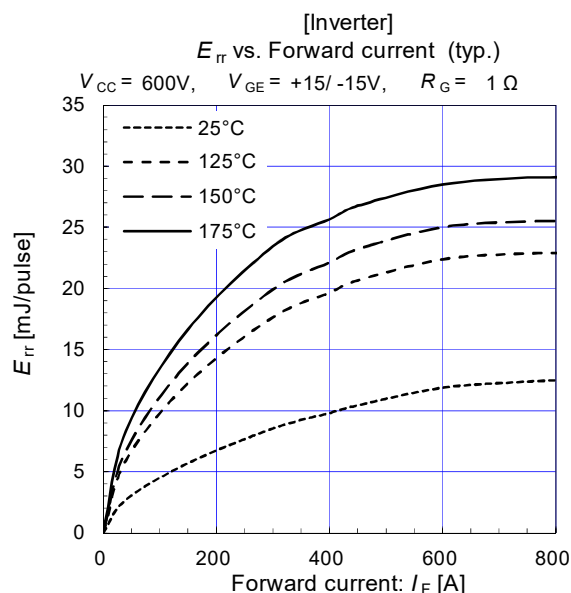
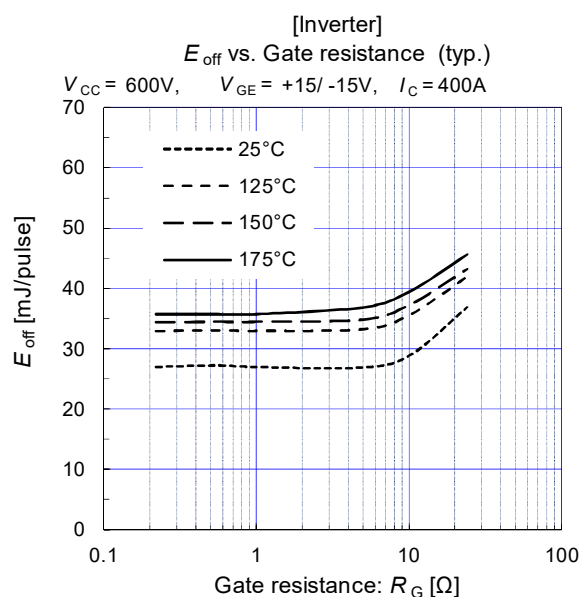
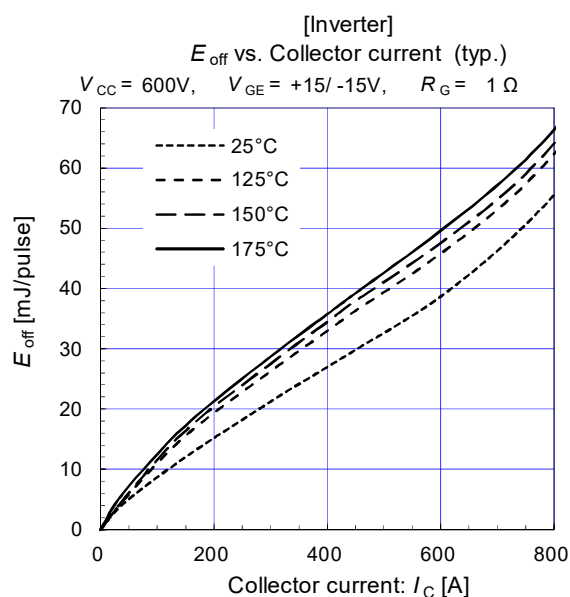
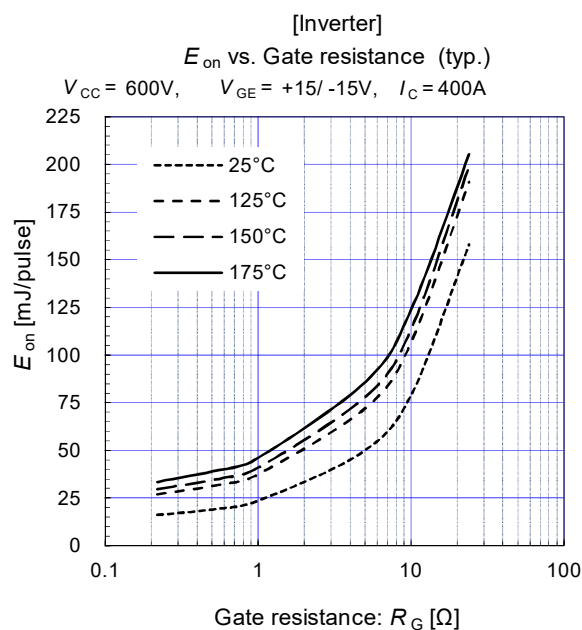
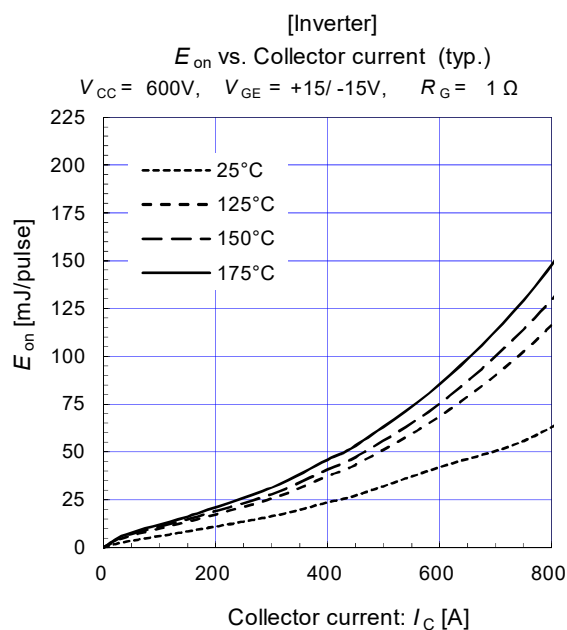
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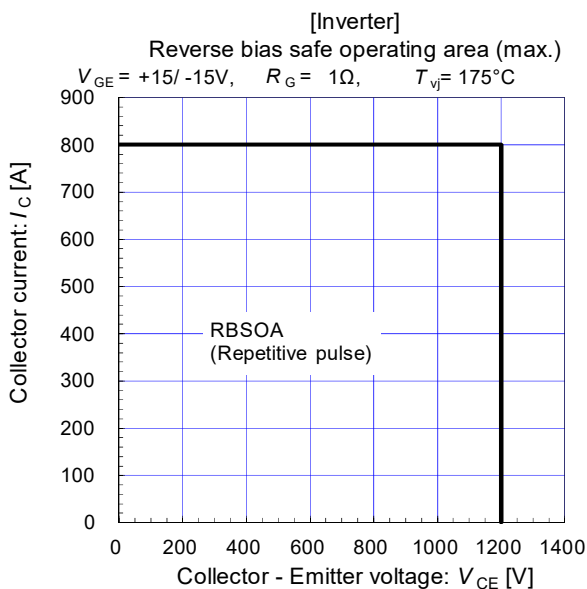
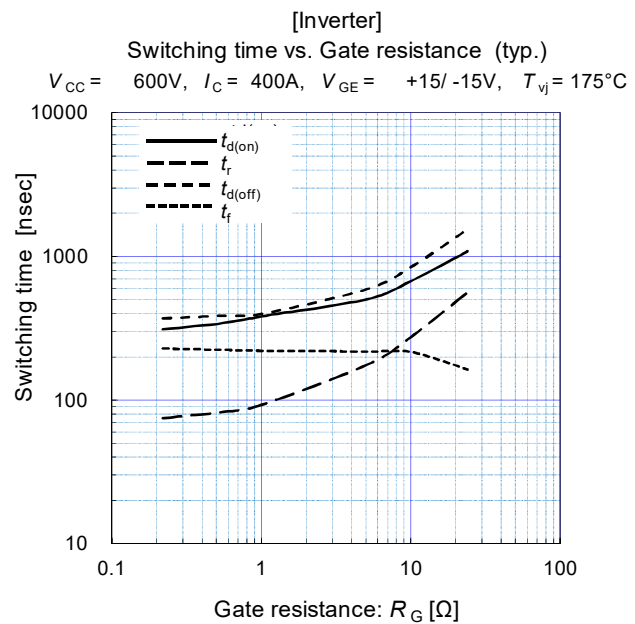
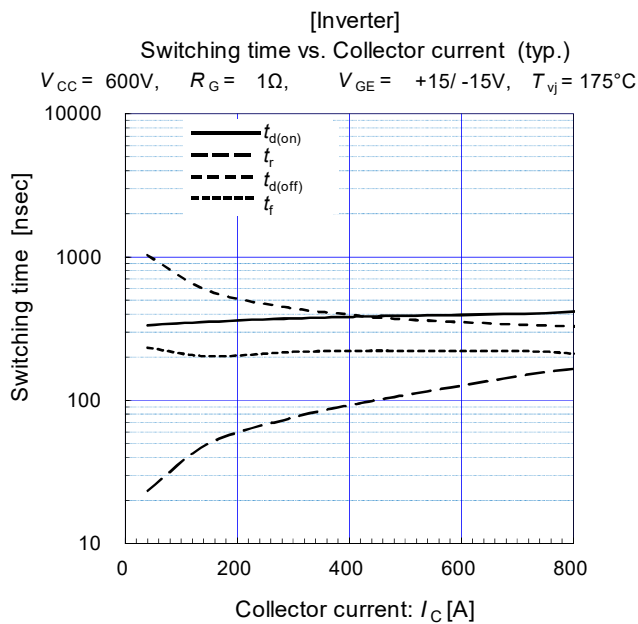
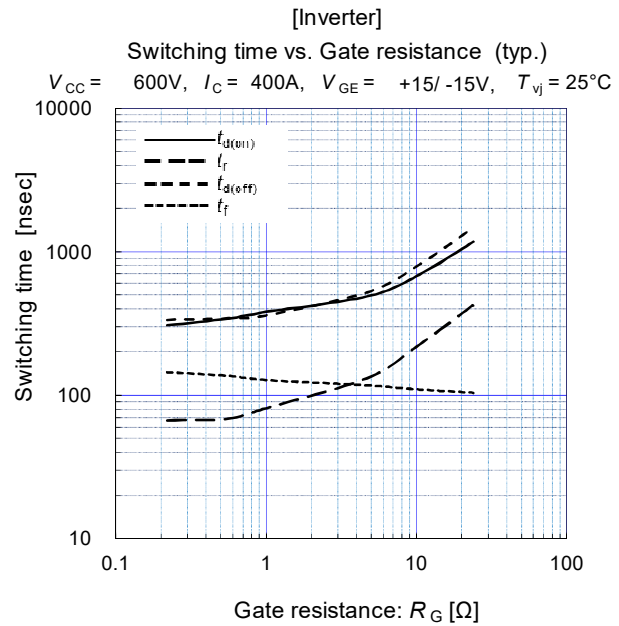
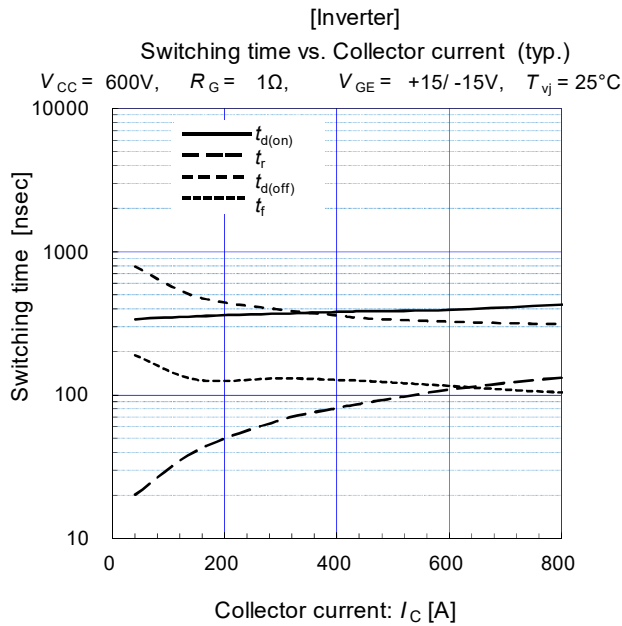
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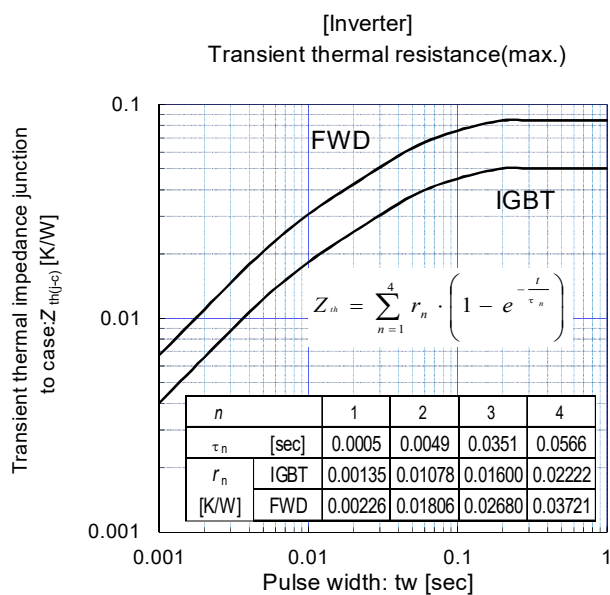
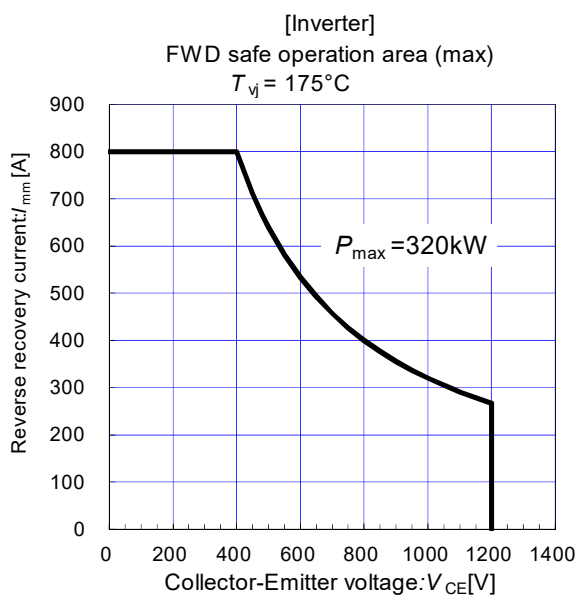
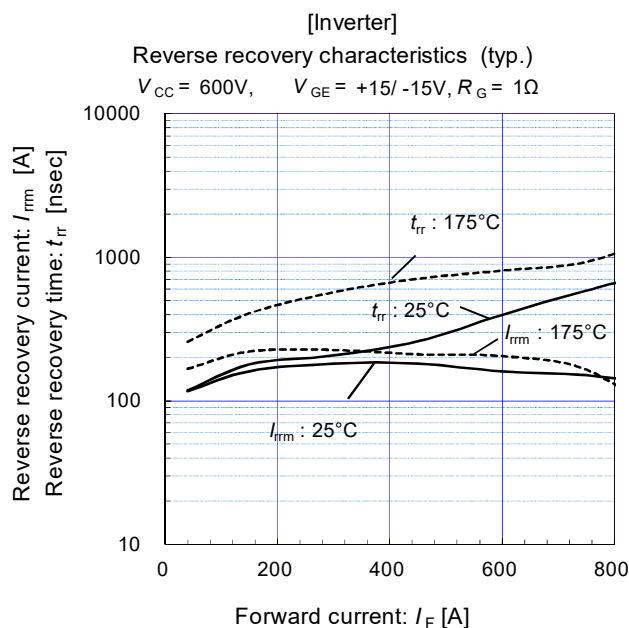
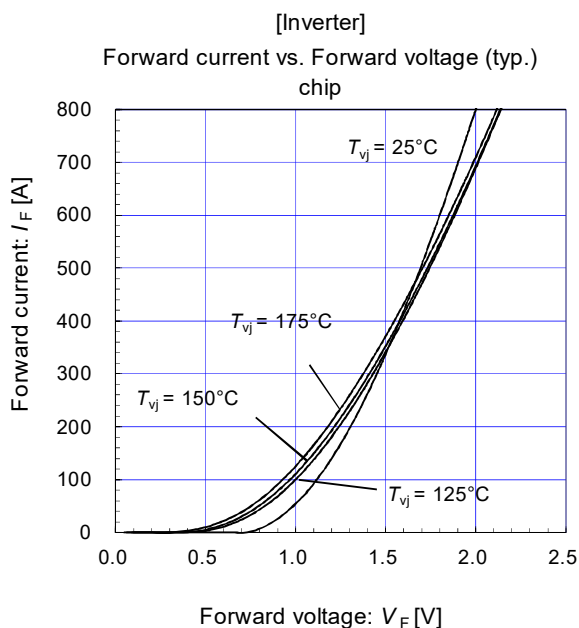
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